

Title (en)
ELECTRONIC ASSEMBLY

Title (de)
ELEKTRONISCHE BAUEINHEIT

Title (fr)
MODULE ÉLECTRONIQUE

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Application
EP 18714488 A 20180328

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Abstract (en)
[origin: WO2018210474A1] The invention relates to an electronic assembly (10), particularly a sensor device, having a housing (12) sealed against the ingress of media, having electronic components (31, 32) arranged in an interior space (14; 14a) of the housing (12) and having a filling element (35; 35a), which extends at least almost as far as the electronic components (31, 32) or is in contact therewith.

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G01S 15/931 (2020.01)

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G01S 15/931 (2013.01); **G01S 2015/937** (2013.01)

Citation (search report)
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